

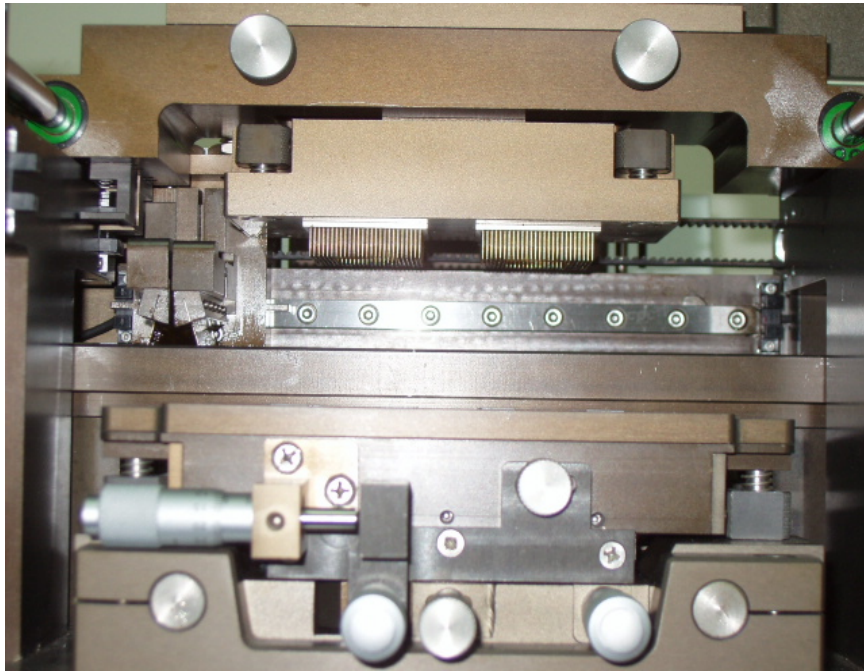
威達誠實業有限公司 WEIDACHENG INDUSYRY CO., LTD

移印錫球植入機 BU-570

植球能力: $0.35\Phi\sim0.76\Phi$ 植球範圍:L-60mm. W-80mm



移印 pin 針座

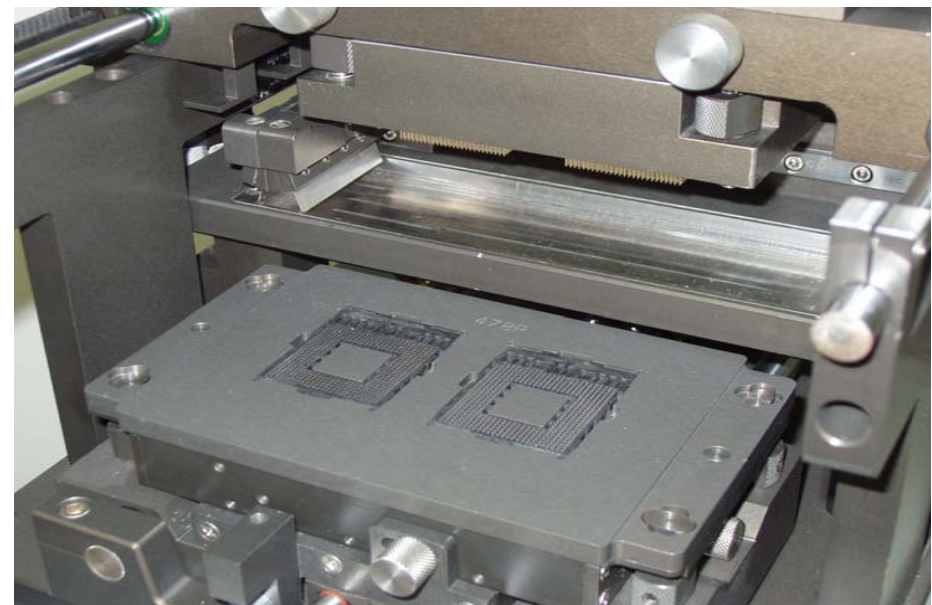


移印刮刀



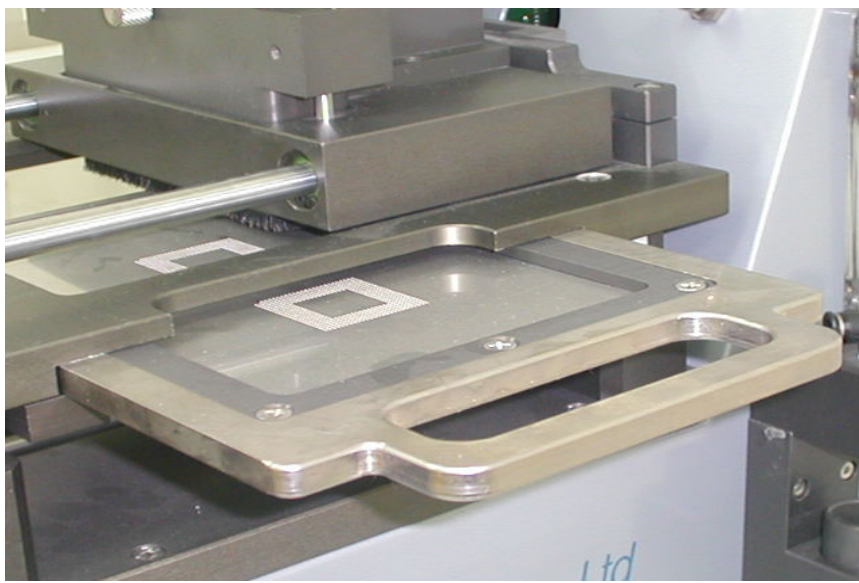
觸控面板-提供功能與數據條件設定

X. Y. θ . 分厘卡調整滑座與腳座模具



卡夾抽取式錫球模具更換座

除球收集瓶座(清球配置)



BGA 再造

BGA regeneration!

~以低廉錫球,重新植入再造完整 BGA~

~ Place solder balls on BGA to regenerate a whole new one with the lowest cost. ~

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BGA rework equipment --- Solder ball placement system BU-570

- (1) 外部尺寸: 84cm(L),X 36cm(W),X 59cm(H)
 - **Outside dimension: 84cm(L), 36cm(W), 59cm(H).**
- (2) 重量: 42 kg.
 - **Weight: 42 kg.**
- (3) 使用電壓: 110/220V 50/60Hz.
 - **Working voltage: 110/220V;50/60Hz**
- (4) 使用氣壓: 6 kg/cm².
 - **Working air pressure: 6 kg/cm².**
- (5) 錫球規格: 依 BGA 不同使用錫球規格而異.
 - **Solder ball specification: According to the solder ball spec being used by different kinds of BGA package.**
- (6) BGA 模具: 依 BGA 不同規格 SIZE 可更換需求 BGA 模具.
 - **BGA IC holder: It is available for changing-over different types of BGA IC holders according to different size or spec of BGA package.**
- (7) BGA 模具: 依 BGA 不同規格 SIZE 可更換需求錫球模具.
 - **Solder ball screening fixture: It is available for changing-over different ball screening fixtures according to different size or spec of solder ball.**
- (7) 錫球植入速度: 錫球植入 BGA-PAD 點可微調控制錫球植入速度.
 - **Solder ball placing speed: The speed for placing solder balls onto BGA pads can be adjusted and fine-tuning controlled.**
- (8) 錫球植入率: 百分之百.
 - **Ball-placing yield rate: 100%.**
- (9) 錫球植入精度: 0.03 mm.
 - **Ball-placing accuracy: 0.03mm.**
- (10) 模具槽退料: 退料速度 30 - 300 mm/S.
 - **BGA IC holder unloading speed: Unloading speed 30~300 mm/s.**
- (11) 自動移印植球時間: 42/sec.
 - **Automatic ball-placing operation cycle time : 42 seconds.**

錫球植入機,未拆下 BGA 重新植入全新錫球,以利重新迴焊維修,本設備提供 SMT 業界進入 BGA 作業技術層次的提昇,本機為 BGA 生產作業得力助手。The solder ball placement system places new solder balls again onto ball removed BGA-IC for new reflowing rework. This equipment provides a technology promotion for traditional BGA operation in SMT industry. It is a very useful tool for BGA production.

本設備榮獲多國專利仿冒必究

[There are patents approved by lots of countries for this equipment. All rights are reserved]

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